To all our customers

Regarding the change of names mentioned in the document, such as Hitachi Electric and Hitachi XX, to Renesas Technology Corp.

The semiconductor operations of Mitsubishi Electric and Hitachi were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.)

Accordingly, although Hitachi, Hitachi, Ltd., Hitachi Semiconductors, and other Hitachi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp.

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Renesas Technology Corp. Customer Support Dept. April 1, 2003



HITACHI SEMICONDUCTOR TECHNICAL UPDATE

Classification of Production	Microcom	omputer		No	TN-H8*-233A/E	Rev	1.0
ТНЕМЕ	Amendments, Deletions, and Additions to H8/3672 Series Hardware Manual when Iss the Second Edition	'	Classification of Information	3. I 4. C	Spec change Supplement of Documents Limitation of Use Change of Mask Change of Production Line		
		Lot No.				Effect	tive Date
PRODUCT NAME	H8/3672 Series Hardware Manual	All Lots	Reference Documents	H8/3672 Series Hardware Manual ADE-602-239A Rev.2.0		From	Now

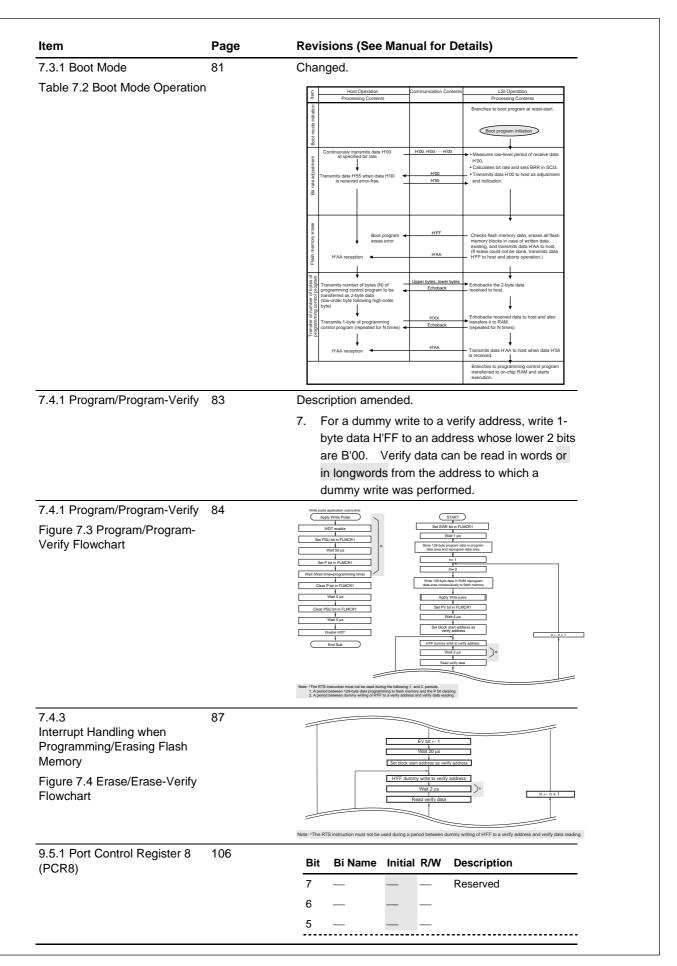
We would like to inform you about the amendments to be made and the descriptions to be deleted and added to the first edition of the H8/3672 Series (H8/3672 and H8/3670) Hardware Manual when issuing the second edition.

Main Revisions and Additions in this Edition

Item	Page	Revisions (See Manual for Details)
General Precautions on Handling of Product	iii	Added.
Configuration of This Manual	iv	Added.
Preface	V	Notes added.
		Restrictions 1 to 5 when using an on-chip emulator (E10T) for H8/3672 program development and debugging
1.1 Features	1	Package added.
Compact package		LQFP-48 (FP-48B)
1.2 Internal Block Diagram	2	↔ E10T_0
Figure 1.1 Internal Block Diagram		↔ E10T_1 ↔ E10T_2
1.3 Pin Arrangement	3	// e Q //
Figure 1.2 Pin Arrangement (FP-64E)		44 43 42 41 40 B 44 41 40 B 44 41 40
		Note: Do not connect NC pins (these pins are not connecte to the internal circuitry).
1.3 Pin Arrangement	4	// e
Figure 1.3 Pin Arrangement (FP-48F, FP-48B)		34 33 32 31 30 34 33 32 31 30
		Note: Do not connect NC pins (these pins are not connecte to the internal circuitry).

Item	Page	Revisions (S	ee I	Manual f	or Deta	IIS)		
1.4 Pin Functions	6	Syrial		TXD	46	36	Out	tpu
Table 1.1 Pin Functions		communication interface (SCI)		RXD	45	35	Inp	ut
			/1 <i>)</i> 	SCK3	44	34	I/O	
1.4 Pin Functions	6		T					
Table 1.1 Pin Functions		E10T E10T_0, E10T_1,	41,	42, 43 31	· · ·	interrace pir emulator	1 for E10	JI
		E10T_2						
2.1 Address Space and Memory Map	8	HD64F	HD64F3672 HD64F3		670	_		
Figure 2.1 Memory Map		H'3FFF						<u> </u>
		H'4000 E10T o program	area		H'4000	E10T co program	area	
		H'4FFF (4 kb)	tes)	<u>-</u>	H'4FFF	(4 kbyt	es)	1
		H'F780		_;	H'F780		=	=
		(1-kbyte w			111 700	(1-kbyte wo		
		for flash programmi				for flash m programming		
					H'FB7F			L
4.1.1 Address Break Control	F.C.							_
Register (ABRKCR)	56	Bit Bit Nar	ne	Descript	tion			
,		4 ACMP2	ACMP2 Address Compare Condition		ondition Se	elect 2 to	0 (
		3 ACMP1		1	•	on condition		
		2 ACMP0		the address b		AR and the	internal	
				000: Com	pares 16-t	oit addresse	s	
				001: Com	pares upp	er 12-bit ad	dresses	
				010: Com	pares upp	er 8-bit add	resses	
				011: Com	pares upp	er 4-bit add	resses	
				1XX: Rese	erved (set	ing prohibit	ed)	
4.2 Operation	58	Description amended. When the ABIF and ABIE bits in ABRKSR are so						
		1, the address break function generates an interequest to the CPU. The ABIF bit in ABRKSR i to 1 by the combination of the address set in B the data set in BDR, and the conditions set in ABRKCR.						
						in		
4.2 Operation	59	Deleted.						
Figure 4.2 Address Break Interrupt Operation Example (3	3)							
4.3 Usage Notes	59	Added.						

Item	Page	Revisions (See Manual for Details)				
5.1 System Clock Generator	61	Added.				
Figure 5.2 Block Diagram of System Clock Generator		OSC2 D LPM LPM: Low-power mode (standby mode, subsleep mode)				
5.2.1 Prescaler S	63	Description amended.				
		In active mode and sleep mode, the clock input to prescaler S is determined by the division factor designated by MA2 to MA0 in SYSCR2.				
6.1.1 System Control Register 1 (SYSCR1)	66	Bit Bit Name Description				
,		6 STS2 Standby Timer Select 2 to 0				
		5 STS1 These bits designate the time the CPU and peripheral modules wait for stable clock operation after exiting from standby mode, to active mode or sleep mode due to an interrupt. The designation should be made according to the clock frequency so that the waiting time is at least 6.5 ms. The relationship between the specified value and the number of wait states is shown in table 6.1. When an external clock is to be used, the minimum value (STS2 = STS1 = STS0 =1) is recommended.				
6.1.4 Module Standby Control Register 2 (MSTCR2)	69	Deleted.				
Section 7 ROM	75	Description amended. EIOT → E10T • Reprogramming capability The flash memory can be reprogrammed up to 1,00 times. Description deleted.				
7.2.4 Flach Mamany Enghla	70	Power-down mode Description amended				
7.2.4 Flash Memory Enable Register (FENR)	79	Description amended. Bit 7 (FLSHE) in FENR enables or disables the CPU access to the flash memory control registers, FLMCR1, FLMCR2, and EBR1.				
7.3 On-Board Programming Modes Table 7.1 Setting Programming	79	Description amended. EIOT_0 → E10T_0				



Item	Page	Revisions (See Manual for Details)			
10.3.2 Time Constant Registers	113	Initial value added. TCORA and TCORB are initialized to H'FF.			
A and B (TCORA, TCORB)					
10.3.5 Timer Control Register V1 (TCRV1)	117	Bit Bit Name Description			
· ,		2 TRGE TCNTV starts counting up by the input o the edge which is selected by TVEG1 and TVEG0.			
		0: Disables starting counting-up TCNTV by the input of the TRGV pin and halting counting-up TCNTV when TCNTV is cleared by a compare match.			
		1: Enables starting counting-up TCNTV by the input of the TRGV pin and halting counting-up TCNTV when TCNTV is cleared by a compare match.			
11.3.2 Timer Control Register	130	Description amended			
W (TCRW)	130	TCRW selects the timer counter clock source, selects a clearing condition, and specifies the timer output levels.			
		Bit Bit Name Initial Value R/W Description			
		3 TOD 0 R/W Timer Output Level Setting D			
		0: Output value is 0*			
		1: Output value is 1*			
		2 TOC 0 R/W Timer Output Level Setting C			
		0: Output value is 0*			
		1: Output value is 1*			
		1 TOB 0 R/W Timer Output Level Setting B			
		0: Output value is 0*			
		1: Output value is 1*			
		0 TOA 0 R/W Timer Output Level Setting A			
		0: Output value is 0*			
		1: Output value is 1*			
		Note: * The change of the setting is immediately reflected in the output value.			
11.4.1 Normal Operation	137	TCNT value //			
Figure 11.6 Toggle Output		†			
Example (TOA = 0, TOB = 1)		H'FFFF			
100 – 1)		GRA			
		GRB HIDDOO			
		H'0000			
12.1 Features	151	Description amended.			
		Selectable from nine counter input clocks.			
		Eight clock sources (φ/64, φ/128, φ/256, φ/512, φ/1024, φ/2048, φ/4096, and φ/8192) or the internal oscillator can be selected as the timer-counter clock When the internal oscillator is selected, it can operate as the watchdog timer in any operating mode.			

Item	Page	Revisions (See Manual for Details)
12.2.1 Timer Control/Status Register WD (TCSRWD)	152	TCSRWD performs the TCSRWD and TCWD write control. TCSRWD also controls the watchdog timer operation and indicates the operating state. TCSRWD must be rewritten by using the MOV instruction. The bit manipulation instruction cannot be used to change the setting value.
		Bit R/W
		7 R/W
		5 R/W
		3 R/W
		1 R/W
13.3.4 Transmit Data Register	158	Initial value added.
(TDR)		TDR is initialized to H'FF.
13.3.7 Serial Status Register (SSR)	163	Bit Bit Name Initial Value R/W
		2 TEND 1 R
15.1 When Using Internal	207	Description amended.
Power Supply Step-Down	201	Connect the external power supply to the V_{∞} pin,
Circuit		and connect a capacitance of approximately 0.1 μ F between V_{cl} and V_{ss} , as shown in figure 15.1.
15.2 When Not Using Internal	208	Description amended.
Power Supply Step-Down Circuit		When the internal power supply step-down circuit is not used, connect the external power supply to the $V_{\rm cL}$ pin and $V_{\rm cc}$ pin, as shown in figure 15.2.
17.2.6 Flash Memory 231 Characteristics (Preliminary)		Values
Table 17.7 Flash Memory		Item Symbol Test Min Typ Max Unit
Characteristics (Preliminary)		Condition
		Reprogramming $N_{\mbox{\tiny MEC}}$ — — 1000 Times count
B.1 I/O Port Block	267	Internal data bus RES SBY
Figure B.10 Port 5 Block Diagram (P54 to P50)		PUCR PMR PDR PCR